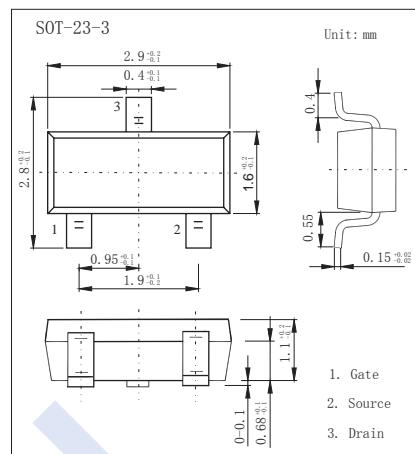
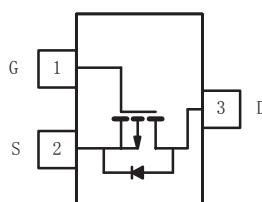


P-Channel Enhancement MOSFET

SI2301DS (KI2301DS)

■ Features

- $V_{DS}(V) = -20V$
- $R_{DS(ON)} < 100m\Omega$ ($V_{GS} = -4.5V$)
- $R_{DS(ON)} < 150m\Omega$ ($V_{GS} = -2.5V$)

■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	5 sec	Steady State	Unit
Drain-Source Voltage	V_{DS}	-20		V
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current $T_a=25^\circ C$ $(T_j=150^\circ C)^*1$	I_D	-3.2	-2.9	A
		-2.5	-2.3	
Pulsed Drain Current *2	I_{DM}	-10		
Power Dissipation *1 $T_a=25^\circ C$ $T_a=70^\circ C$	P_D	0.9	0.7	W
		0.57	0.45	
Thermal Resistance.Junction- to-Ambient *1 *3	R_{thJA}	120	145	°C/W
		140	175	
Junction Temperature	T_J	150		°C
Storage Temperature Range	T_{stg}	-55 to 150		

*1 Surface Mounted on FR4 Board, $t \leq 5$ sec.

*2 Pulse width limited by maximum junction temperature.

*3 Surface Mounted on FR4 Board.

P-Channel Enhancement MOSFET

SI2301DS (KI2301DS)

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D = -250 \mu\text{A}, V_{GS} = 0\text{V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$		-1		μA
		$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}, T_J = 55^\circ\text{C}$		-10		
Gate-Body leakage current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 8\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-0.45		-0.95	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{V}, I_D = -2.8\text{A}$		80	100	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}, I_D = -2.0\text{A}$		110	150	
On state drain current *1	$I_{D(ON)}$	$V_{GS} = -4.5\text{V}, V_{DS} \leq -5\text{V}$	-6			A
		$V_{GS} = -2.5\text{V}, V_{DS} \leq -5\text{V}$	-3			
Forward Transconductance *1	g_{FS}	$V_{DS} = -5\text{V}, I_D = -2.8\text{A}$		6.5		S
Input Capacitance *2	C_{iss}	$V_{GS} = 0\text{V}, V_{DS} = -6\text{V}, f = 1\text{MHz}$		375		pF
Output Capacitance *2	C_{oss}			95		
Reverse Transfer Capacitance *2	C_{rss}			65		
Total Gate Charge *2	Q_g	$V_{GS} = -4.5\text{V}, V_{DS} = -6\text{V}, I_D = -2.8\text{A}$		4.5	10	nC
Gate Source Charge *2	Q_{gs}			0.7		
Gate Drain Charge *2	Q_{gd}			1.1		
Turn-On DelayTime *3	$t_{d(on)}$	$V_{GS} = -4.5\text{V}, V_{DS} = -6\text{V}, R_L = 6\Omega, R_{GEN} = 6\Omega$ $I_D = -1.0\text{A}$		20	30	ns
Turn-On Rise Time *3	t_r			40	60	
Turn-Off DelayTime *3	$t_{d(off)}$			30	45	
Turn-Off Fall Time *3	t_f			20	30	
Maximum Body-Diode Continuous Current	I_S	5 sec			-0.72	A
		Steady State			-0.6	
Diode Forward Voltage	V_{SD}	$I_S = -0.75\text{A}, V_{GS} = 0\text{V}$		-0.8	-1.2	V

*1 Pulse test: $PW \leq 300\text{us}$ duty cycle $\leq 2\%$.

*2 For DESIGN AID ONLY, not subject to production testing.

*3 Switching time is essentially independent of operating temperature.

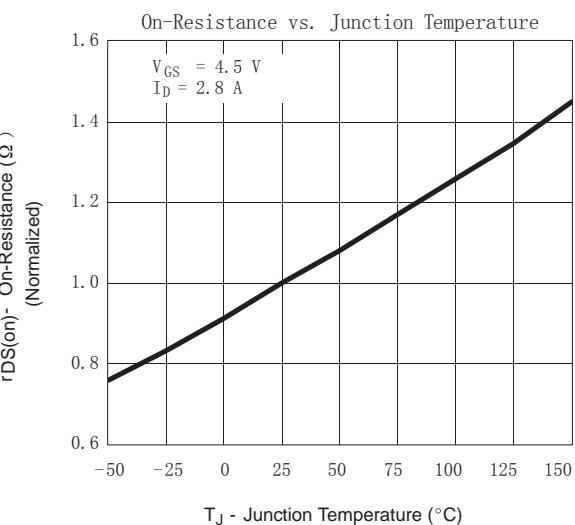
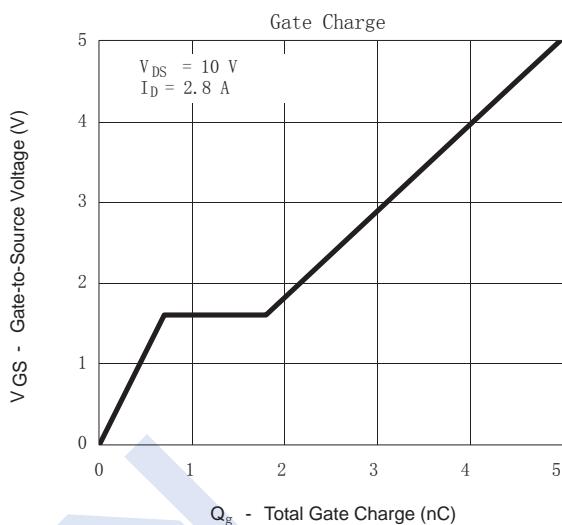
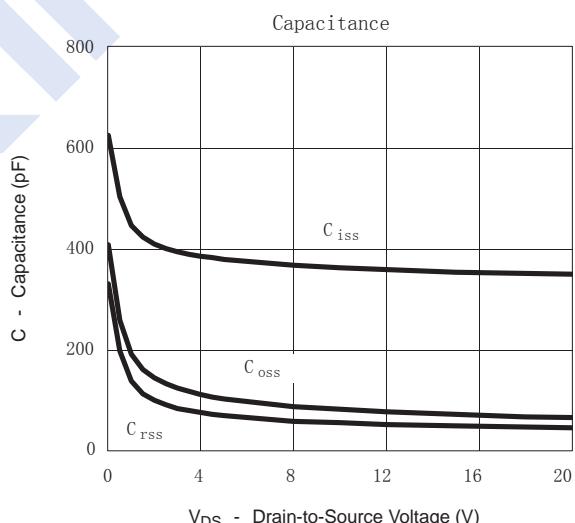
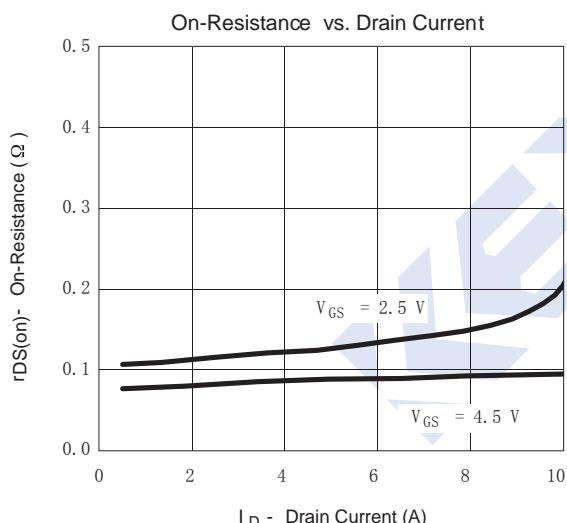
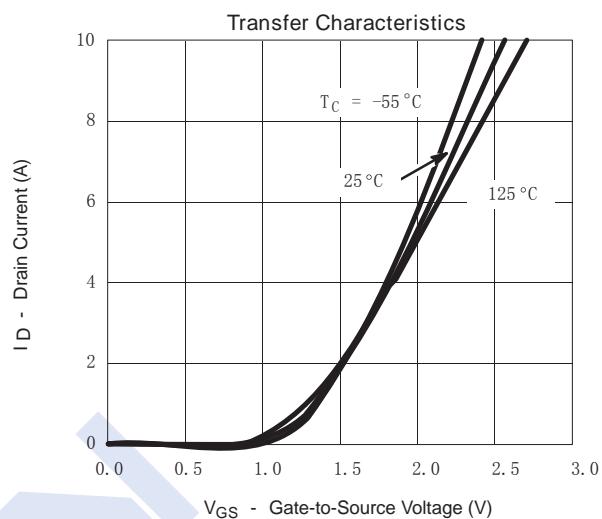
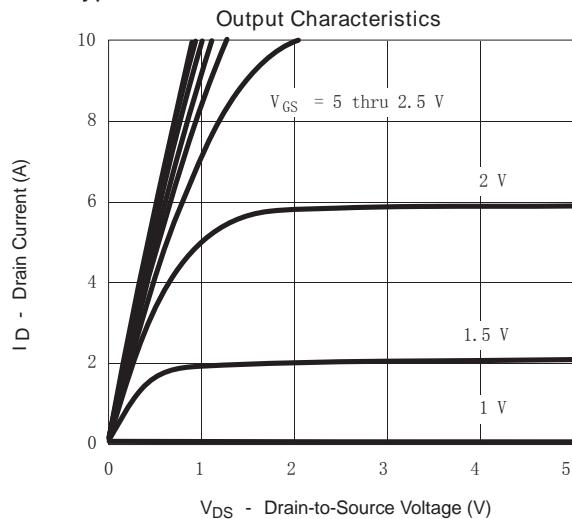
■ Marking

Marking	A1*
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P-Channel Enhancement MOSFET

SI2301DS (KI2301DS)

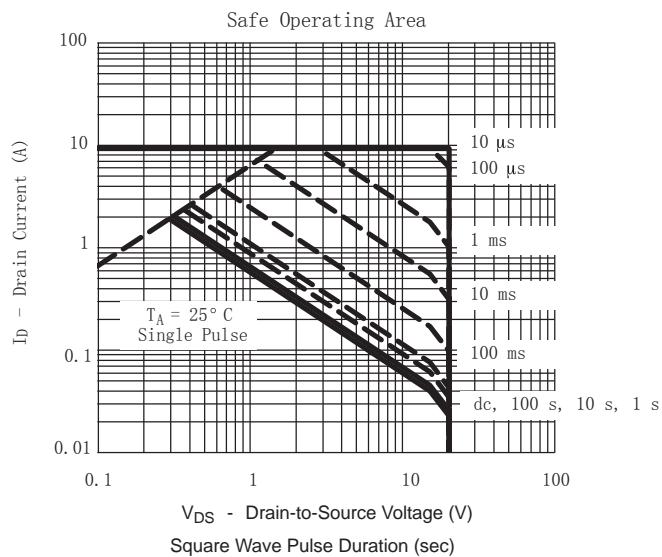
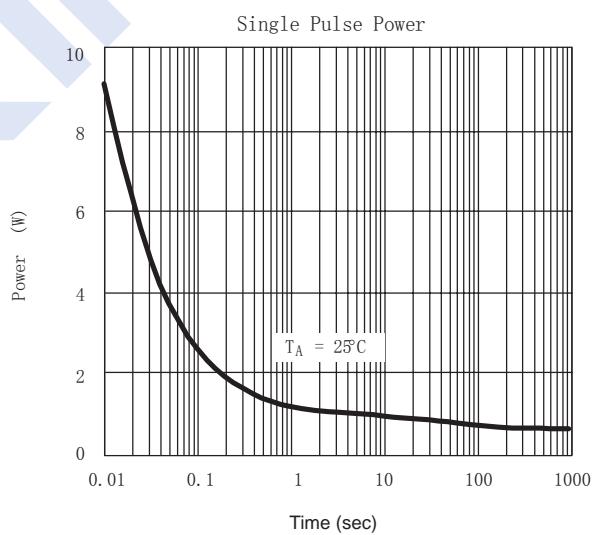
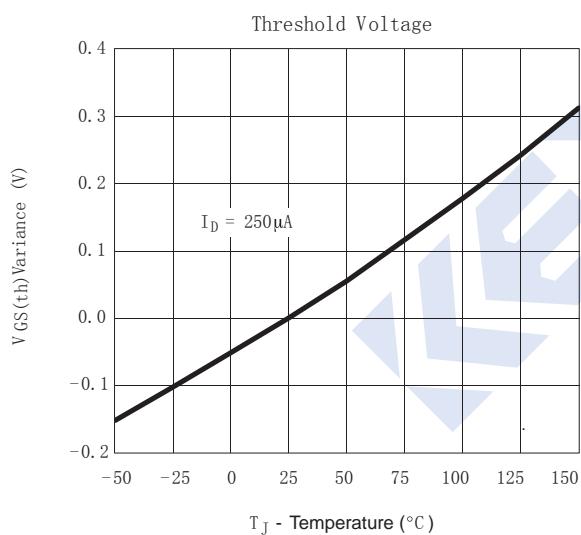
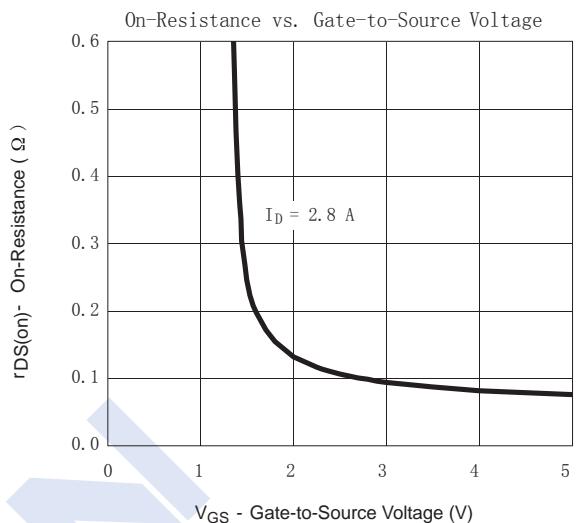
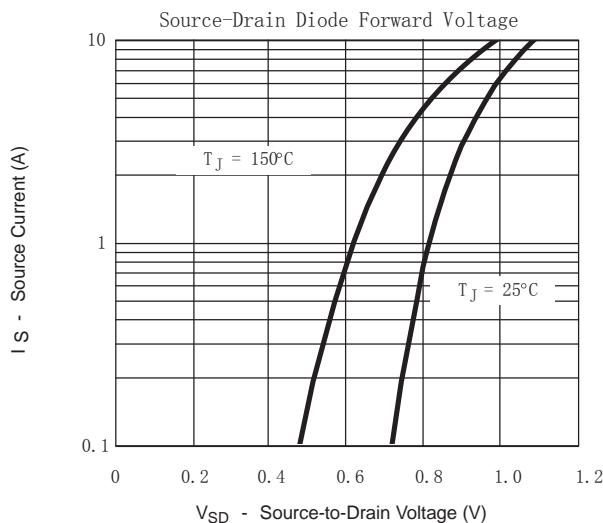
■ Typical Characteristics



P-Channel Enhancement MOSFET

SI2301DS (KI2301DS)

■ Typical Characteristics



P-Channel Enhancement MOSFET
SI2301DS (KI2301DS)

■ Typical Characteristics

